Premix Thermoplastics PREBOARD E1026 Standard Epoxy Circuit Boards

Category : Polymer , Thermoset , Epoxy

Material Notes:

PREBOARD is a thermoplastic based PCB laminate. Low dissipation factor leads to high gain in the antennas. As a non filled laminate PREBOARD is fully homogenous so that consistant properties are achieved through the whole panel even at high frequencies. Temperature stability in processing and long term stability in service at elevated temperatures are good. It also has low moisture absorption. PREBOARD is offered as custom sized panels according to customer specifications. Also thin films made of the same material are available and marketed under the name PREFLEX. Thus the same material can also be used in rigid/flex boards. The material lends itself also well for injection moulding and is available for that purpose in granules sold under the name PREPERM. This enables the production of 3D circuit boards to customer specification. Normally low temperature solders are recommended. Soldering with standard non lead solders has been demonstrated with fixtures.Key features:Low and stable dissipation factor Low and stable dielectric constantLow water absorptionHigh TgRecyclable and RoHS compliantEasier to process than PTFEGood thermal resistanceLow CTE in all directionsFlame retardant UL 94-V0Applications: cellular phone base stations, cell phone antenna frames and similar antennas and other RF and microwave devices. Also halogen free flame retardant UL-V0 grade is available.Information from Premix OY

Order this product through the following link:
http://www.lookpolymers.com/polymer_Premix-Thermoplastics-PREBOARD-E1026-Standard-Epoxy-Circuit-Boards.php

Physical Properties	Metric	English	Comments
Density	1.06 g/cc	0.0383 lb/in³	ASTM D792
Water Absorption	0.40 %	0.40 %	TM650 2.6.2.1

Mechanical Properties	Metric	English	Comments
Tensile Strength	55.0 MPa	7980 psi	ISO 527
Tensile Modulus	2.30 GPa	334 ksi	ISO 527
Flexural Modulus	2.20 GPa	319 ksi	ISO 178

Thermal Properties	Metric	English	Comments
CTE, linear	50.0 µm/m-°C	27.8 µin/in-°F	
Heat Distortion Temperature	195 °C	383 °F	
Glass Transition Temp, Tg	197 °C	387 °F	TM650 2.4.25
	210 °C	410 °F	
Flammability, UL94	V-0	V-0	

Electrical Properties	Metric	English	Comments
Volume Resistivity			TM650 2.5.17.1

Electrical Properties	Metric	English	Comments
Surface Resistance	2.00e+8 ohm-cm	2.00e+8 ohm-cm	TM650 2.5.17.1
Dielectric Constant	2.6 @Frequency 1.00e+9 - 1.00e+10 Hz	2.6 @Frequency 1.00e+9 - 1.00e+10 Hz	TM650 2.5.5.9
Dissipation Factor	0.0020 @Frequency 1.00e+9 - 1.00e+10 Hz	0.0020 @Frequency 1.00e+9 - 1.00e+10 Hz	

Descriptive Properties	Value	Comments
Copper Peel Strength (N/mm)	1	IPE-TM650 2.4.8
Dimensional Stability (%)	<0.2	150°C/2h

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com
Email : sales@lookpolymers.com
Tel : +86 021-51131842
Mobile : +86 13061808058
Skype : lookpolymers
Address : United North Road 215,Fengxian District, Shanghai City,China